

ASPIDES

<u>A CMOS SPAD and Digital SiPM Platform for High Energy Physics</u> (proposta di esperimento)

Responsabile nazionale: Lodovico Ratti (sez. di Pavia)

INFN Pavia, Consiglio di Sezione, 3 luglio 2024, Pavia

ASPIDES project

Goal:

develop SiPMs in CMOS technology (digital SiPMs or dSiPMs) for fast (high time density), high dynamic range counting and high accuracy timing – application to dual readout calorimetry, RICH, dark matter and neutrino experiments

Participating units:

Bari (N. Mazziotta), Bologna (L. Rignanese), Milano (R. Santoro), Pavia (L. Ratti), Trento (L. Pancheri), Napoli (G. Fiorillo), Padova (G. Collazuol), Torino (M. Da Rocha Rolo)

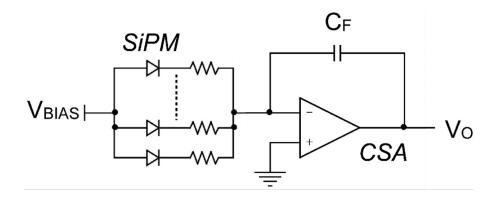
Research area:

Detectors and electronics

Duration: 3 years

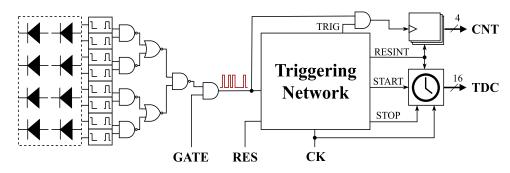
SiPMs: analog vs digital

 Analog SiPMs: signal proportional to number of fired cells – real time detection



- ✓ Inherently fast circuits, allowing the detection of photons with **high temporal density**
- X High power consumption, need for a converter to digital domain

 Digital (CMOS) SiPMs: NAND/NOR compression trees, binary counters, serialized pulses from fired cells



M. Perenzoni et al. 2017 - IEEE JSSC

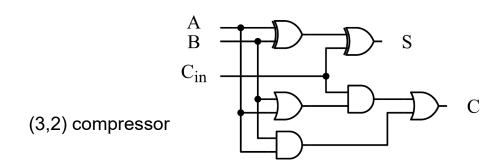
- ✓ No static power consumption, standardized design, standard cells, no A/D converters, open to new features
- Problems with detection of photons with high temporal density

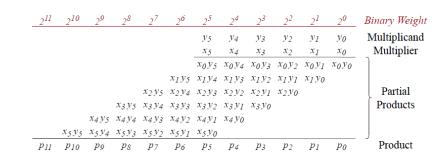
Parallel counters

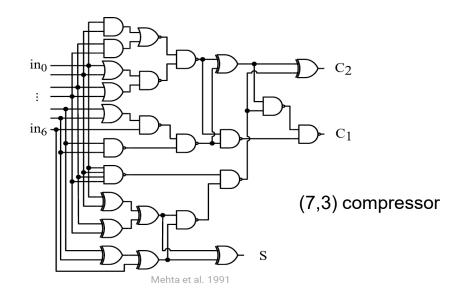
"A **Parallel Counter** is a combinational network which provides q outputs, processing the signals coming from its $p \le 2^q - 1$ inputs. The binary number represented by the q outputs is the number of bit at 1 fed as inputs"

L. Dadda, "On Parallel Digital Multipliers", Alta Frequenza, 1976

(n,m) compressors are devices capable of collapsing n input lines into m output lines interpreted as the binary representation of the number of ones at the input $(m \ge \lceil \log 2 \rceil)$





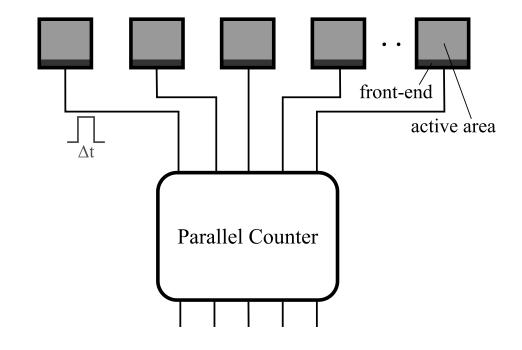


Parallel counter based dSiPM (flash-dSiPM)

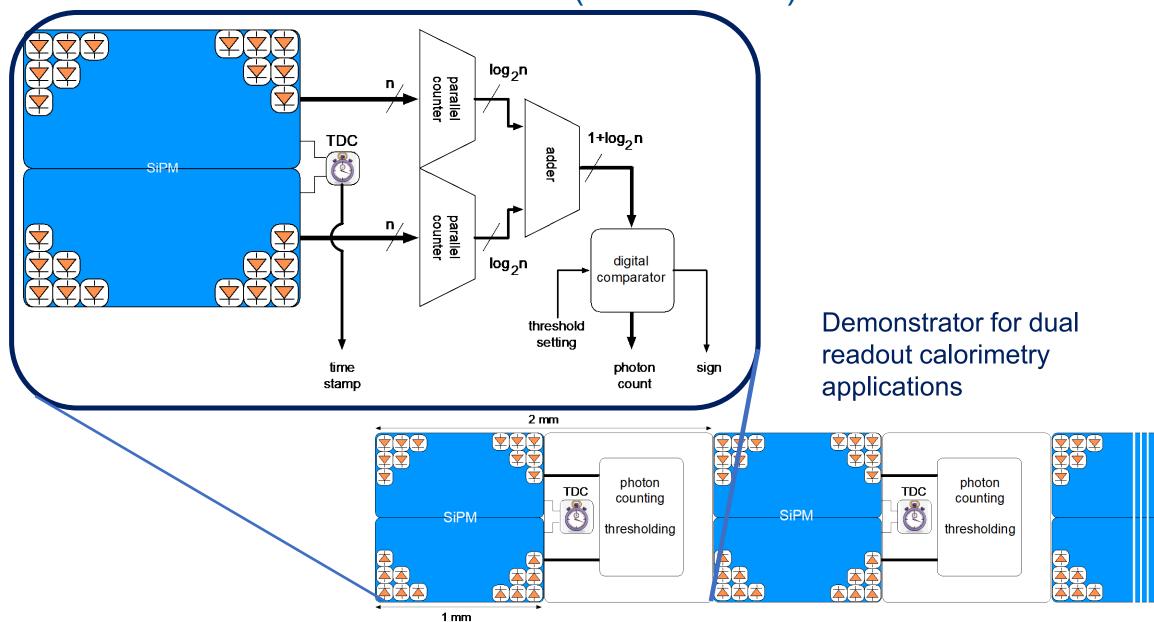
SiPMs based on high-speed combinational networks, low latency, real time photon counting from simultaneously fired SPADs

The integration of parallel counters in dSiPM structures brings several **challenges**:

- large number of parallel connections from SPAD cells
- poor modularity
- balanced signal paths
 - reduction of glitches (spurious pulses)
 - power consumption optimization
- area optimization
- delay optimization



Parallel counter based dSiPM (flash-dSiPM)



Fully digital approach – Pros and Cons

Pros

- Measurement result immediately available in digital form
- No need for additional readout chips to be coupled to the sensor
- Easier linearization and calibration direct digital output vs digital/analog (including noise + non uniformity)/digital conversion
- Integrated TDC local timing signal generation and measurement
- Smaller costs for large areas

Cons

- Readout architecture has poor modularity
- Fill factor may suffer from small pitch and readout circuit complexity

Specifications

Requirements	Dual readout calorimetry	Cherenkov (eg RICH, IACT)	DM	neutrino
SiPM Unit area (mm^2)	1x1	mm scale	10x10	6x6
Micro-cell pitch (um)	10-15	40-50	25-30	50-150
Macro-pixel area (um^2)	500x500			
PDE (%)	>20	> 40	>45	>35
DCR (kHz)	<100 kHz/mm²	very low for single pe detection	<0.1 Hz/mm² (at LN)	<0.2 Hz/mm² (at LN)
AP (%)	<1	few		<5%
Xtalk (%)	few	few	Total Correlated Noise Probability (Xtalk + AP) < 60 %	<35%
Trigger	external, self	self, external	self	
Output data: light intensity	no. of fired cells in 1 or 2 time windows (10's of ns long)			
Output data: time	time of arrival of the first photon in the window, possibly of the last photon (TOT)	ToA and ToT	ToA and TOT	
Time resolution (ps)	<100	< 100 single pe		
Module size and form factor	strip with 8 units (1mm x 16 mm), pitch of 2 mm			
Connection	BGA			

Activity program

- Characterization of the ASAP110LF test chip developed in a 110 nm CMOS technology, including different SPAD arrays with different features (passive and active quenching, different active area, structures for investigating timing properties and ionizing radiation tolerance) and mini-SiPMs
 - DCR, breakdown voltage, afterpulsing, electrical and optical cross-talk, also as a function of the temperature
 - QE and PDP/PDE
 - Time resolution
- Investigation of the cumulative damage from ionizing radiation (X-ray) and from atomic dislocation in the substrate (neutrons, protons)
- Study of SPAD operation in cryogenic conditions

Activity program

- Development of small scale prototypes of CMOS SiPMs consisting of about 1000 SPADs with 15-20 um
- o for the readout, both a fully digital and a mixed analog and digital approach will be explored best compromise between detection efficiency (fill factor) and functional density
- on sensor electronics to be provided with event detection, counting, thresholding and time stamping capabilities, possibly together with the ability to follow the time evolution of the light pulses reconstruction of the longitudinal shower and discrimination between Cherenkov and scintillation signals
- specific structures included to test the chip functionalities
- submission 3Q 2025, characterization 1Q 2026
- Development of a demonstrator chip including 8 SiPMs, each with a 1 mm² area and a 2 mm pitch (64x64 cells, 15 um pitch) dual readout calorimetry
- o inter-SiPM region used for integrating most of the electronics, to minimize the impact on the fill-factor
- o smaller versions of dSiPMs for application to RICH, DM and neutrino experiments (larger SiPMs)
- characterization to be performed in the lab and in a beam test
- submission 4Q 2026, characterization 2Q-4Q 2027

Personnel involved in the experiment

PAVIA

Roberto Ferrari: 5%

Lodovico Ratti: 40%

Fatemeh Shojaei: 100%

Carla Vacchi: 20%

Sezione	FTE
Bari	>1
Bologna	0.3
Milano	1.0
Napoli	1.3
Padova	0.4
Pavia	1.65
Torino	0.35
Trento	1.2
TOTALE	>7.2

Financial request (PV, 2025)

		k€
Missioni	missioni a Bologna per meeting su interfacciamento con DAQ; missioni a Torino per meeting su circuiti di front-end per SiPM digitale	2
Consumi	Run MPW con LFoundry, 12 mm ² (2.52 kEuro/mm ²)	41
	Produzione di schede di test per collaudo di circuiti integrati	5
	packaging di 10 chip	3
Totale		51

Financial request (PV, 2026-2027)

		k€
Missioni	missioni a Bologna per meeting su interfacciamento con DAQ; missioni a Torino per meeting su circuiti di front-end per SiPM digitale	3
	Partecipazione a test beam (2 persone per 1 settimana)	3
Consumi	Run MPW con LFoundry, 25 mm² (2.52 kEuro/mm²)	77
	Produzione di schede di test per collaudo di circuiti integrati	8
	packaging di 10 chip	3
Totale		94

Non sono richiesti servizi di sezione

Financial request (overall)

	2025	2026-2027
Missioni	~15 kEuro	~40 kEuro
Consumi	~75 kEuro	~140 kEuro
Totale	~90 kEuro	~180 kEuro